

# FGH20N60UFD

## 600 V, 20 A Field Stop IGBT

### Features

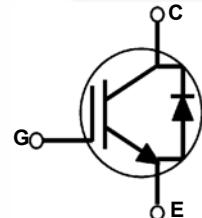
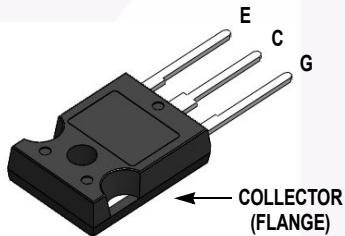
- High Current Capability
- Low Saturation Voltage:  $V_{CE(sat)} = 1.8 \text{ V}$  @  $I_C = 20 \text{ A}$
- High Input Impedance
- Fast Switching
- RoHS Compliant

### Applications

- Solar Inverter, UPS, Welder, PFC

### General Description

Using novel field stop IGBT technology, Fairchild's field stop IGBTs offer the optimum performance for solar inverter, UPS, welder and PFC applications where low conduction and switching losses are essential.



### Absolute Maximum Ratings

Symbol	Description	Ratings	Unit
$V_{CES}$	Collector to Emitter Voltage	600	V
$V_{GES}$	Gate to Emitter Voltage	$\pm 20$	V
$I_C$	Collector Current @ $T_C = 25^\circ\text{C}$	40	A
	Collector Current @ $T_C = 100^\circ\text{C}$	20	A
$I_{CM(1)}$	Pulsed Collector Current @ $T_C = 25^\circ\text{C}$	60	A
$I_F$	Diode Forward Current @ $T_C = 25^\circ\text{C}$	20	A
	Diode Forward Current @ $T_C = 100^\circ\text{C}$	10	A
$I_{FM(1)}$	Pulsed Diode Maximum Forward Current	60	A
$P_D$	Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$	165	W
	Maximum Power Dissipation @ $T_C = 100^\circ\text{C}$	66	W
$T_J$	Operating Junction Temperature	-55 to +150	$^\circ\text{C}$
$T_{stg}$	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

**Notes:**

1: Repetitive rating: Pulse width limited by max. junction temperature

## Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGH20N60UFDTU	FGH20N60UFD	TO-247	Tube	N/A	N/A	30

## Electrical Characteristics of the IGBT $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
$\text{BV}_{\text{CES}}$	Collector to Emitter Breakdown Voltage	$V_{\text{GE}} = 0 \text{ V}$ , $I_C = 250 \mu\text{A}$	600	-	-	V
$\frac{\Delta \text{BV}_{\text{CES}}}{\Delta T_J}$	Temperature Coefficient of Breakdown Voltage	$V_{\text{GE}} = 0 \text{ V}$ , $I_C = 250 \mu\text{A}$	-	0.6	-	$\text{V}^\circ\text{C}$
$I_{\text{CES}}$	Collector Cut-Off Current	$V_{\text{CE}} = \text{V}_{\text{CES}}$ , $V_{\text{GE}} = 0 \text{ V}$	-	-	250	$\mu\text{A}$
$I_{\text{GES}}$	G-E Leakage Current	$V_{\text{GE}} = \text{V}_{\text{GES}}$ , $V_{\text{CE}} = 0 \text{ V}$	-	-	$\pm 400$	nA
<b>On Characteristics</b>						
$V_{\text{GE}(\text{th})}$	G-E Threshold Voltage	$I_C = 250 \mu\text{A}$ , $V_{\text{CE}} = V_{\text{GE}}$	4.0	5.0	6.5	V
$V_{\text{CE}(\text{sat})}$	Collector to Emitter Saturation Voltage	$I_C = 20 \text{ A}$ , $V_{\text{GE}} = 15 \text{ V}$	-	1.8	2.4	V
		$I_C = 20 \text{ A}$ , $V_{\text{GE}} = 15 \text{ V}$ , $T_C = 125^\circ\text{C}$	-	2.0	-	V
<b>Dynamic Characteristics</b>						
$C_{\text{ies}}$	Input Capacitance	$V_{\text{CE}} = 30 \text{ V}$ , $V_{\text{GE}} = 0 \text{ V}$ , $f = 1 \text{ MHz}$	-	940	-	pF
$C_{\text{oes}}$	Output Capacitance		-	110	-	pF
$C_{\text{res}}$	Reverse Transfer Capacitance		-	40	-	pF
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{CC}} = 400 \text{ V}$ , $I_C = 20 \text{ A}$ , $R_G = 10 \Omega$ , $V_{\text{GE}} = 15 \text{ V}$ , Inductive Load, $T_C = 25^\circ\text{C}$	-	13	-	ns
$t_r$	Rise Time		-	17	-	ns
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		-	87	-	ns
$t_f$	Fall Time		-	32	64	ns
$E_{\text{on}}$	Turn-On Switching Loss		-	0.38	-	mJ
$E_{\text{off}}$	Turn-Off Switching Loss		-	0.26	-	mJ
$E_{\text{ts}}$	Total Switching Loss		-	0.64	-	mJ
$t_{\text{d}(\text{on})}$	Turn-On Delay Time		-	13	-	ns
$t_r$	Rise Time	$V_{\text{CC}} = 400 \text{ V}$ , $I_C = 20 \text{ A}$ , $R_G = 10 \Omega$ , $V_{\text{GE}} = 15 \text{ V}$ , Inductive Load, $T_C = 125^\circ\text{C}$	-	16	-	ns
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		-	92	-	ns
$t_f$	Fall Time		-	63	-	ns
$E_{\text{on}}$	Turn-On Switching Loss		-	0.41	-	mJ
$E_{\text{off}}$	Turn-Off Switching Loss		-	0.36	-	mJ
$E_{\text{ts}}$	Total Switching Loss		-	0.77	-	mJ
$Q_g$	Total Gate Charge	$V_{\text{CE}} = 400 \text{ V}$ , $I_C = 20 \text{ A}$ , $V_{\text{GE}} = 15 \text{ V}$	-	63	-	nC
$Q_{\text{ge}}$	Gate to Emitter Charge		-	7	-	nC
$Q_{\text{gc}}$	Gate to Collector Charge		-	32	-	nC

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$ (IGBT)	Thermal Resistance, Junction to Case	-	0.76	°C/W
$R_{\theta JC}$ (Diode)	Thermal Resistance, Junction to Case	-	2.51	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

### Electrical Characteristics of the Diode $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max	Unit
$V_{FM}$	Diode Forward Voltage	$I_F = 10 \text{ A}$	$T_C = 25^\circ\text{C}$	-	1.9	2.5
			$T_C = 125^\circ\text{C}$	-	1.7	-
$t_{rr}$	Diode Reverse Recovery Time	$I_F = 10 \text{ A}, \text{di}_F/\text{dt} = 200 \text{ A}/\mu\text{s}$	$T_C = 25^\circ\text{C}$	-	34	-
			$T_C = 125^\circ\text{C}$	-	57	-
$Q_{rr}$	Diode Reverse Recovery Charge		$T_C = 25^\circ\text{C}$	-	41	-
			$T_C = 125^\circ\text{C}$	-	96	-

## Typical Performance Characteristics

Figure 1. Typical Output Characteristics

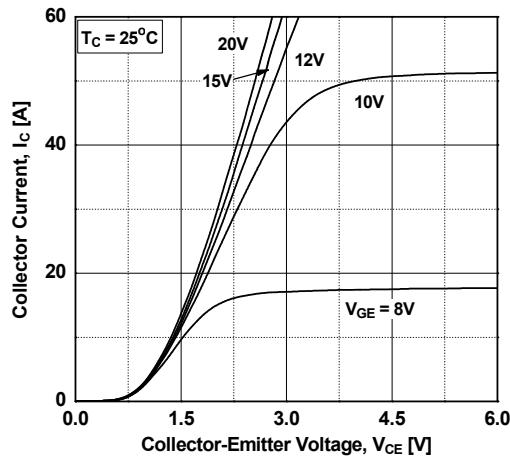


Figure 2. Typical Output Characteristics

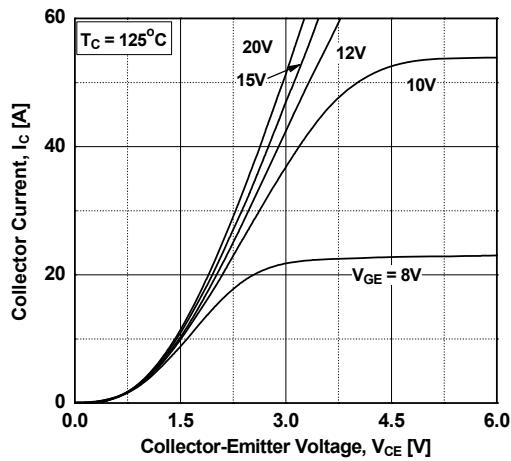


Figure 3. Typical Saturation Voltage Characteristics

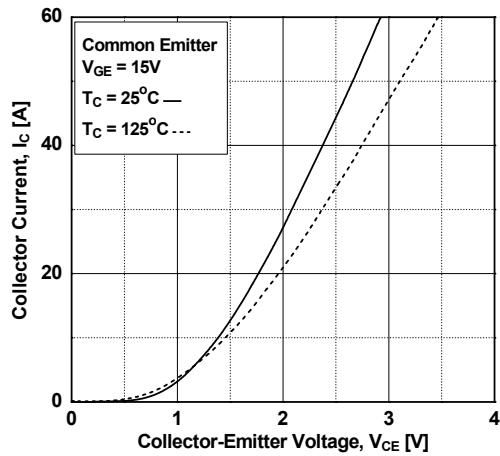


Figure 4. Transfer Characteristics

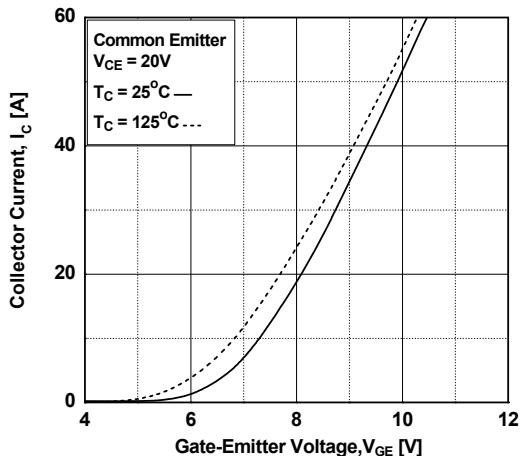


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

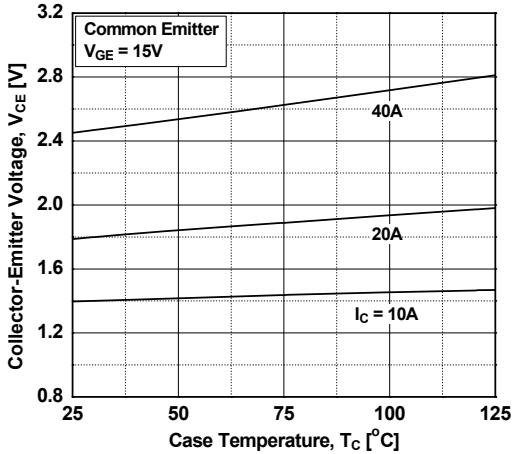
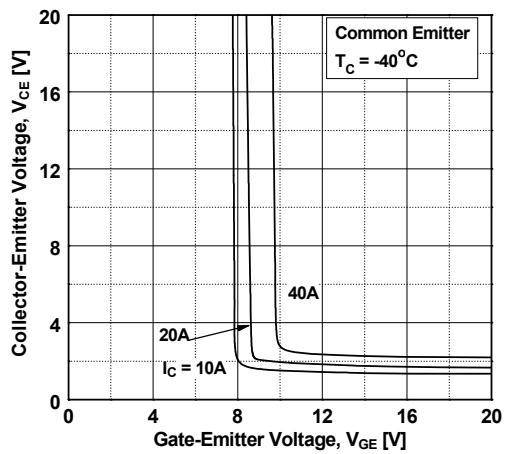


Figure 6. Saturation Voltage vs.  $V_{GE}$



## Typical Performance Characteristics

Figure 7. Saturation Voltage vs.  $V_{GE}$

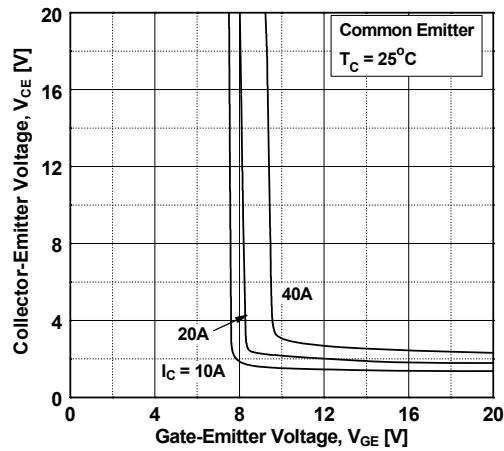


Figure 8. Saturation Voltage vs.  $V_{GE}$

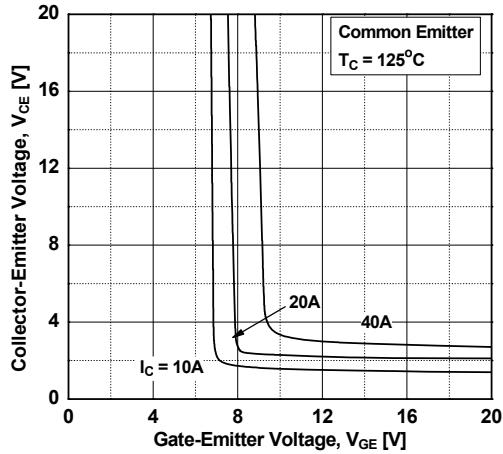


Figure 9. Capacitance Characteristics

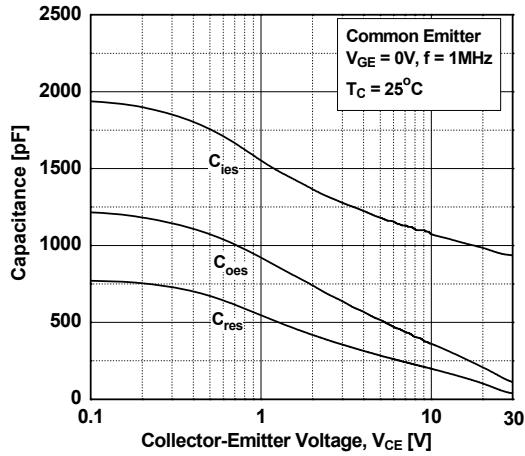


Figure 10. Gate charge Characteristics

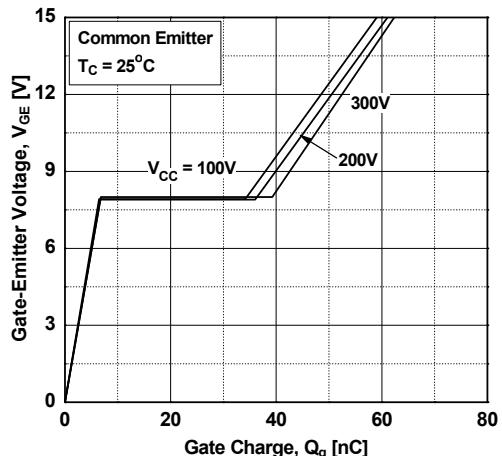


Figure 11. SOA Characteristics

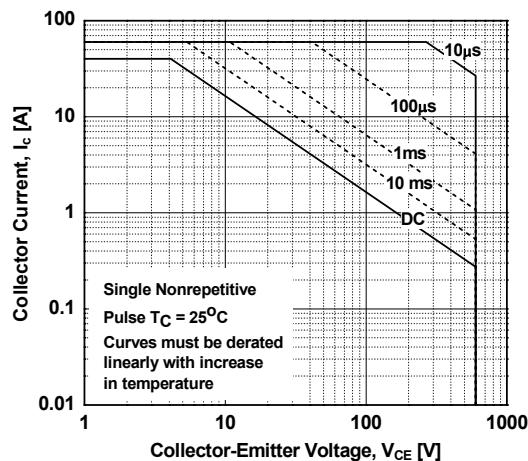
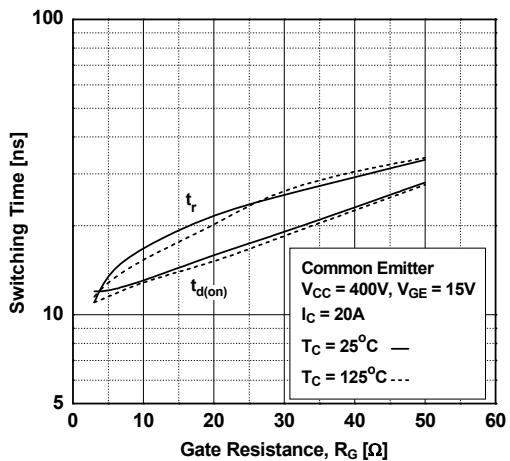


Figure 12. Turn-on Characteristics vs. Gate Resistance



## Typical Performance Characteristics

Figure 13. Turn-off Characteristics vs. Gate Resistance

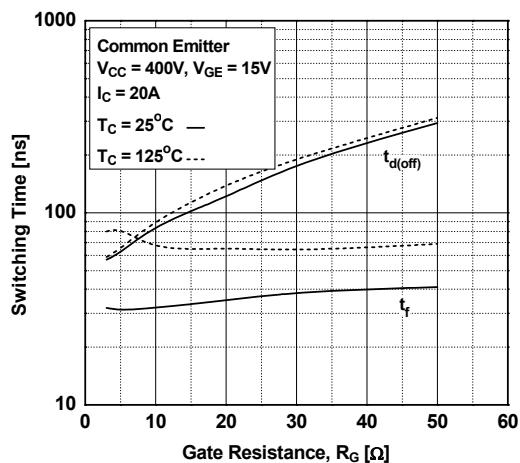


Figure 14. Turn-on Characteristics vs. Collector Current

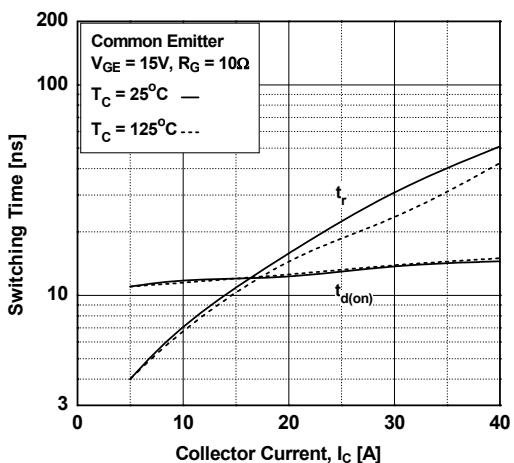


Figure 15. Turn-off Characteristics vs. Collector Current

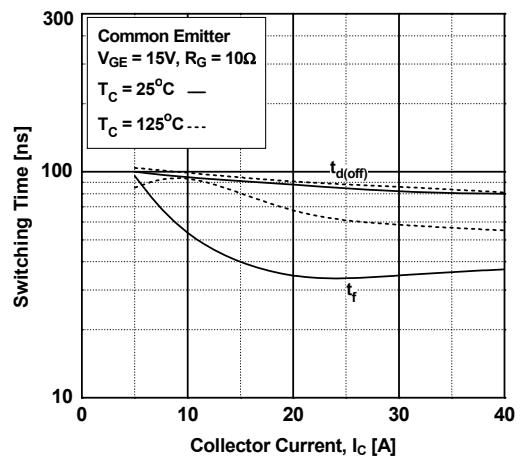


Figure 16. Switching Loss vs. Gate Resistance

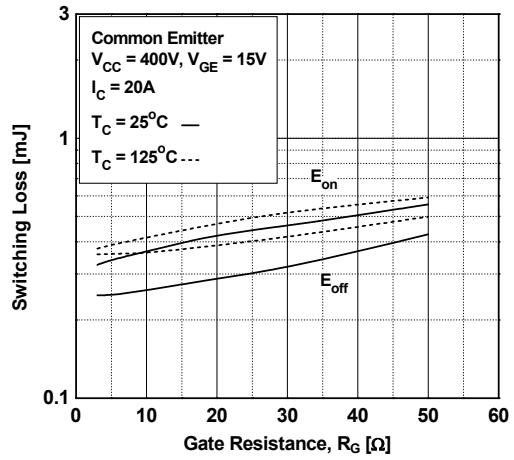


Figure 17. Switching Loss vs. Collector Current

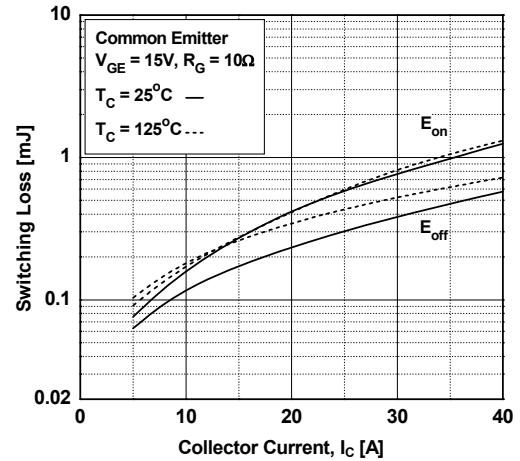
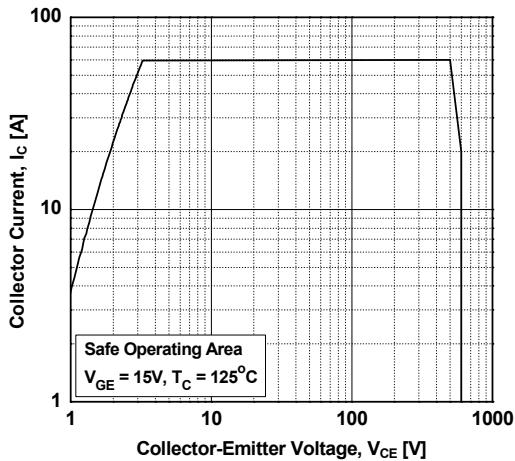


Figure 18. Turn off Switching SOA Characteristics



## Typical Performance Characteristics

Figure 19. Forward Characteristics

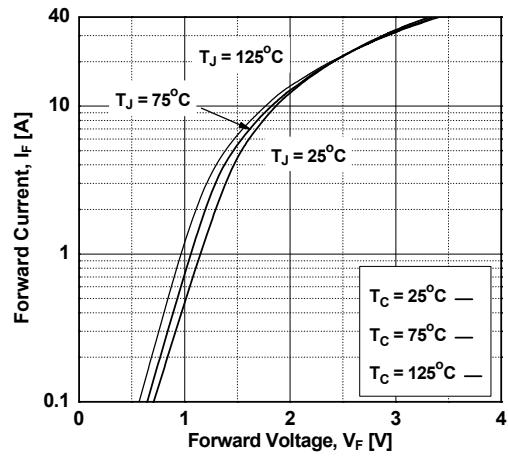


Figure 20. Reverse Current

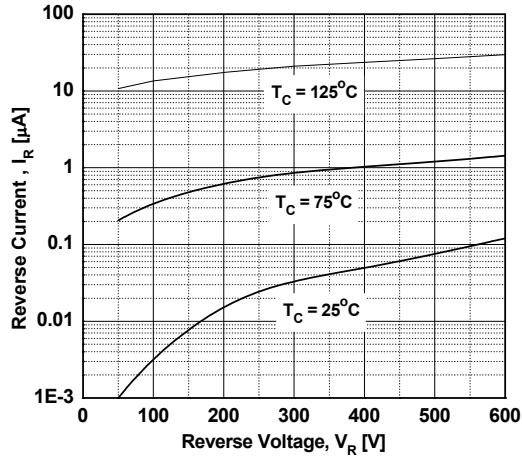


Figure 21. Stored Charge

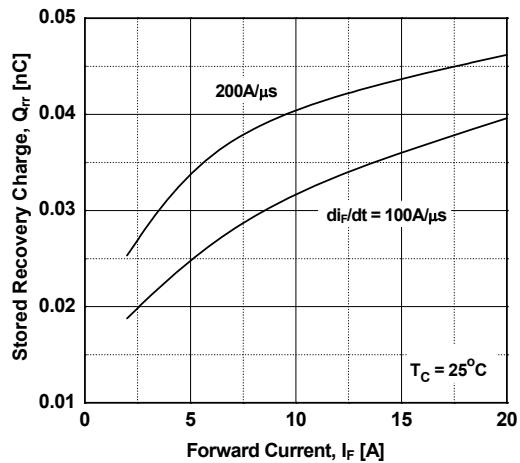


Figure 22. Reverse Recovery Time

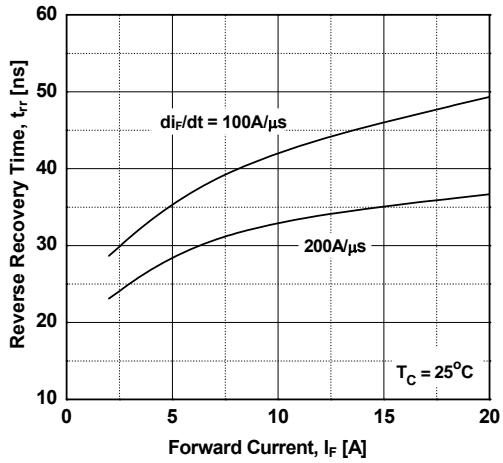
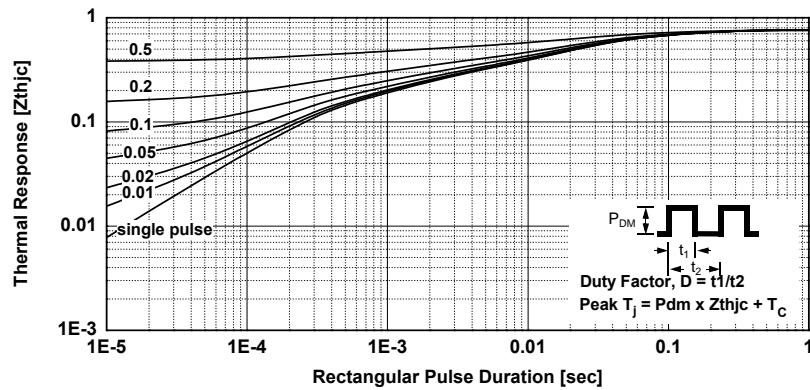
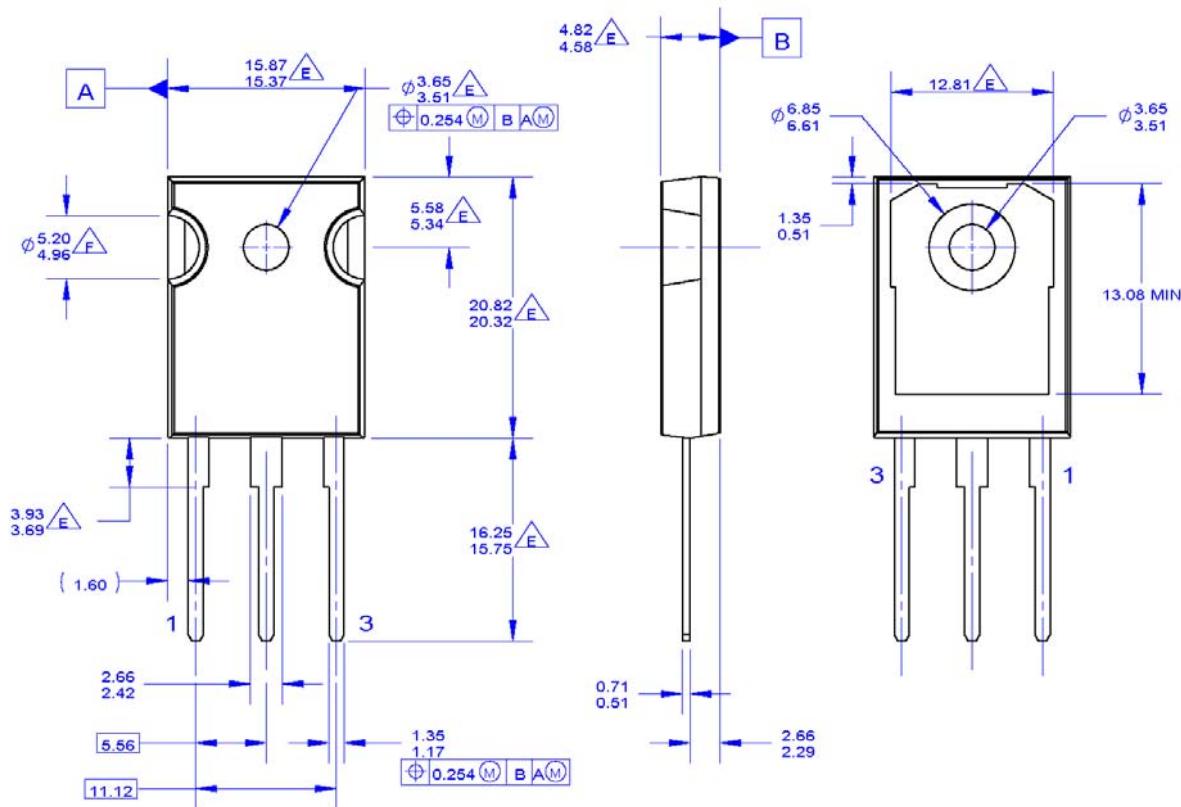


Figure 23. Transient Thermal Impedance of IGBT



## Mechanical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. PACKAGE REFERENCE: JEDEC TO-247,  
ISSUE E, VARIATION AB, DATED JUNE, 2004.
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD  
FLASH, AND TIE BAR EXTRUSIONS.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DRAWING CONFORMS TO ASME Y14.5 - 1994

 DOES NOT COMPLY JEDEC STANDARD VALUE

 NOTCH MAY BE SQUARE

G. DRAWING FILENAME: MKT-T0247A03\_REV03

**Figure 24. TO-247 3L - TO-247, MOLDED, 3 LEAD, JEDEC VARIATION AB**

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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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